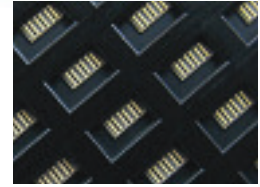


For RF Noise Suppression in high speed mixed signal semiconductor devices



Miniature RF Blocking Network

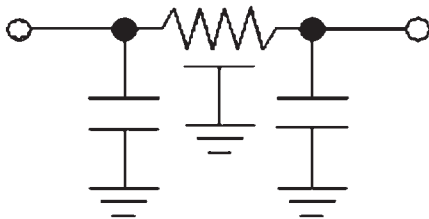
Functional Applications:

- High Speed Digital
- Mixed Signal IC's
- Suppression of Noise on DC Supply Lines
- MCM and Hybrid Modules

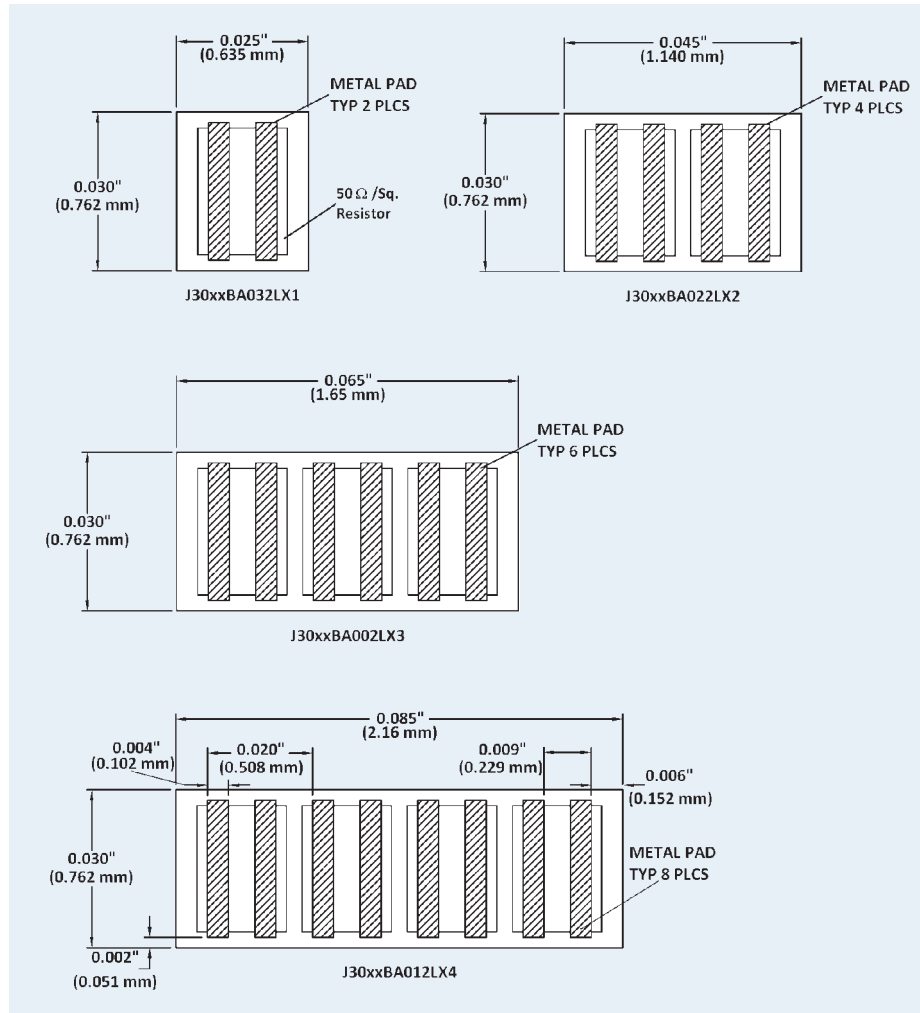
Benefits:

- Eliminates Noise at I/O Pins
- Replaces Large Decoupling Capacitor with Superior Performance
- Clean DC Lines Beyond 18 GHz

Segment Equivalent Schematic Representation



Layout and Dimensions



Part Number Identification

J	30	XX	BA01	2	L	X	4
Product J = Blocking Network	Width (Mils)	Material BL or BJ	Internal Drawing Reference	Voltage 2 = 25 Vdc	Metallization 100μ" Gold Finish	Test Level Commercial	Number of RC Segments

Material and Electrical Characteristics

Material Code	Capacitance (typical)	Resistance (pad to pad)	DF	TCC	Rated Voltage
BL	30 pF	10Ω Nom.	3.0% Max.	X7R	25 Vdc
BJ	45 pF	10Ω Nom.	3.0% Max.	X7R	25 Vdc

Miniature RF Blocking Network

Metallization:

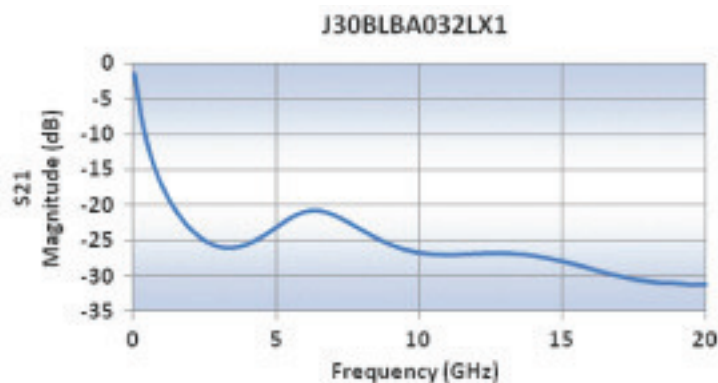
Top: 50/Square TaN, 300Å TiW, 100 • Inch minimum Au.

Bottom: 300Å TiW, 100 • Inch minimum Au.

Screening Options

Test Code	Test/Inspection	Sample Size	Description
X	Bond Strength	2 Pcs/Plate	2 bonding pads on each sample
	IR	1% AQL	2 1/2 times rated voltage of 25 volts
	Visual Inspection	100%	4 Side visual screening
	Pad to pad resistance check	1% AQL	Ensure isolation between segments and boarder

Performance



Segment Bonding for Measurement



For additional data of multi-segment devices please contact an inside sales representative.

Typical Application

